

PRODUCT NO.	DIM. A	DIM. B	PLATING ON CONTACT	RECOMMENDED PGB THK.
10029860-003	3.05	3.43	15u GOLD	2.36mm (.093")
10029860-003LF	3.05	3.43	15u GOLD	2.36mm (.093")
10029860-013LF	3.05	3.43	30u GOLD	2.36mm (.093")

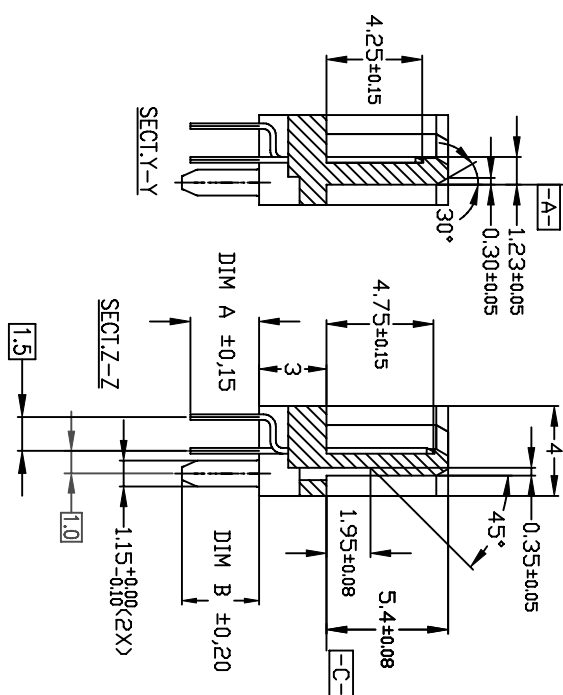
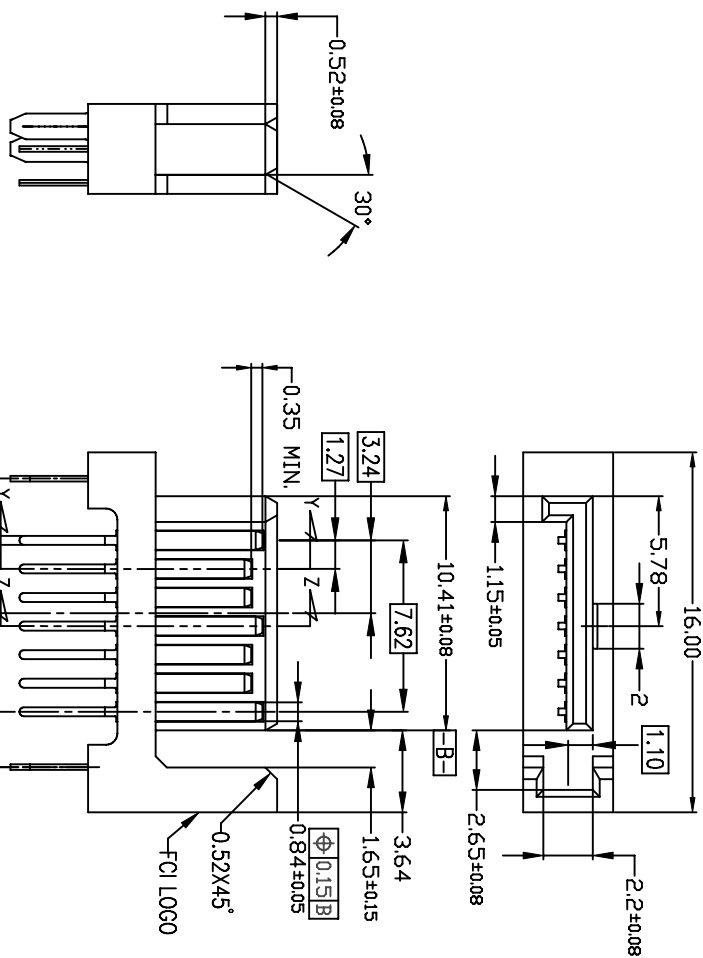
1-2

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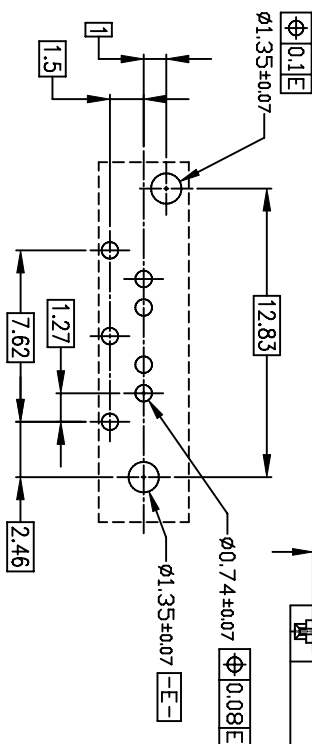
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NOTE

1. THIS PRODUCT MEETS THE SATA SPEC REV. 1.0a
2. MATERIAL – i) HOUSING : HIGH TEMP. THERMOPLASTIC UL94V-0
ii) TERMINAL : COPPER ALLOY
iii) HOLD DOWN : COPPER ALLOY
3. FINISH – i) TERMINAL : Au PLATING AT CONTACT POINT Sn-Pb PLATING 100u”
MIN AT SOLDER TAIL WITH NICKEL UNDERPLATE
ii) HOLD DOWN : Sn-Pb PLATING
4. P/N: 10028860-XXXXF REFER TO LEADFREE PRODUCT.
i) TERMINAL : Au PLATING AT CONTACT POINT Sn PLATING 100u” MIN AT
SOLDER TAIL WITH NICKEL UNDERPLATE
ii) HOLD DOWN : Sn PLATING
5. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10
SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MINIMUM THICK CIRCUIT
BOARD.
6. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10
SECONDS IN A CONVECTION, INFRARED OR VAPOR PHASE REFLOW OVEN.
7. FOR 10028860-XXXXF, THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.



RECOMMENDED MOUNTING LAYOUT
RECOMMENDED PCB T = SEE TABLE
TOLERANCE UNLESS OTHERWISE NOTED.



mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY			
ltr	ecn no	dr	dtde	.X ± 0.38		projection		title	
A	S04-0217	HLW	10/18/04	.XX ± 0.25				S-ATA SIGNAL PLUG DIP VERTICAL TYPE ASS'Y	
B	S04-0249	HLW	11/19/04	.XXX ± 0.15					
C	S05-0048	YSS	02/22/05	0° ±2°					
D	T06-0135	S.Lin	07/17/06	dr	UPEH	06/25/03	product family		
				engr	YEO SS	02/22/05	EDGE CARD		
				chr	YEO SS	02/22/05	size dwg no		
				appr	JOEY NG	02/22/05	10028860		
sheet	revision	D					TWN		
index	sheet	1					sheet 1 of 1		

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